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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Discontinued at Digi-Key
Number of LABs/CLBs	250540
Number of Logic Elements/Cells	660000
Total RAM Bits	49610752
Number of I/O	588
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10ax066n4f40i3sges



Feature	Description	
Embedded Hard IP blocks	Variable-precision DSP	<ul style="list-style-type: none">Native support for signal processing precision levels from 18 x 19 to 54 x 54Native support for 27 x 27 multiplier mode64-bit accumulator and cascade for systolic finite impulse responses (FIRs)Internal coefficient memory banksPadder/subtractor for improved efficiencyAdditional pipeline register to increase performance and reduce powerSupports floating point arithmetic:<ul style="list-style-type: none">Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication.Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability.Dynamic accumulator reset control.Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.
	Memory controller	DDR4, DDR3, and DDR3L
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port
	Transceiver I/O	<ul style="list-style-type: none">10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC)PCS hard IPs that support:<ul style="list-style-type: none">10-Gbps Ethernet (10GbE)PCIe PIPE interfaceInterlakenGbps Ethernet (GbE)Common Public Radio Interface (CPRI) with deterministic latency supportGigabit-capable passive optical network (GPON) with fast lock-time support13.5G JESD204b8B/10B, 64B/66B, 64B/67B encoders and decodersCustom mode support for proprietary protocols
Core clock networks	<ul style="list-style-type: none">Up to 800 MHz fabric clocking, depending on the application:<ul style="list-style-type: none">667 MHz external memory interface clocking with 2,400 Mbps DDR4 interface800 MHz LVDS interface clocking with 1,600 Mbps LVDS interfaceGlobal, regional, and peripheral clock networksClock networks that are not used can be gated to reduce dynamic power	
Phase-locked loops (PLLs)	<ul style="list-style-type: none">High-resolution fractional synthesis PLLs:<ul style="list-style-type: none">Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)Support integer mode and fractional modeFractional mode support with third-order delta-sigma modulationInteger PLLs:<ul style="list-style-type: none">Adjacent to general purpose I/OsSupport external memory and LVDS interfaces	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none">1.6 Gbps LVDS—every pair can be configured as receiver or transmitterOn-chip termination (OCT)1.2 V to 3.0 V single-ended LVTTTL/LVCMOS interfacing	
External Memory Interface	<ul style="list-style-type: none">Hard memory controller—DDR4, DDR3, and DDR3L support<ul style="list-style-type: none">DDR4—speeds up to 1,200 MHz/2,400 MbpsDDR3—speeds up to 1,067 MHz/2,133 MbpsSoft memory controller—provides support for RLDRAM 3⁽²⁾, QDR IV⁽²⁾, and QDR II+	
continued...		



Feature	Description
	<ul style="list-style-type: none">Dynamic reconfiguration of the transceivers and PLLsFine-grained partial reconfiguration of the core fabricActive Serial x4 Interface
Power management	<ul style="list-style-type: none">SmartVIDLow static power device optionsProgrammable Power TechnologyIntel Quartus Prime integrated power analysis
Software and tools	<ul style="list-style-type: none">Intel Quartus Prime design suiteTransceiver toolkitPlatform Designer system integration toolDSP Builder for Intel FPGAsOpenCL™ supportIntel SoC FPGA Embedded Design Suite (EDS)

Related Information

[Intel Arria 10 Transceiver PHY Overview](#)

Provides details on Intel Arria 10 transceivers.

Intel Arria 10 Device Variants and Packages

Table 4. Device Variants for the Intel Arria 10 Device Family

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	FPGA featuring: <ul style="list-style-type: none">17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

[Intel FPGA Product Selector](#)

Provides the latest information on Intel products.



Available Options

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



Maximum Resources

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

Resource		Product Line				
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements (LE) (K)		160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830	985	1,368
18 x 19 Multiplier		312	384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Transceiver		12	12	24	24	36
GPIO ⁽³⁾		288	288	384	384	492
LVDS Pair ⁽⁴⁾		120	120	168	168	222
PCIe Hard IP Block		1	1	2	2	2
Hard Memory Controller		6	6	8	8	12

⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.

**Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)			F35 (35 mm × 35 mm, 1152-pin FBGA)			KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	—	—	—	—	—	—
GX 320	48	336	24	48	336	24	—	—	—	—	—	—
GX 480	48	444	24	48	348	36	—	—	—	—	—	—
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	—	504	24	—	—	—	—	—	—	—	600	48
GX 1150	—	504	24	—	—	—	—	—	—	—	600	48

Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)			NF45 (45 mm × 45 mm) 1932-pin FBGA)			SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 900	—	342	66	—	768	48	—	624	72	—	480	96
GX 1150	—	342	66	—	768	48	—	624	72	—	480	96

Related Information

[I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook](#)

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 GT

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

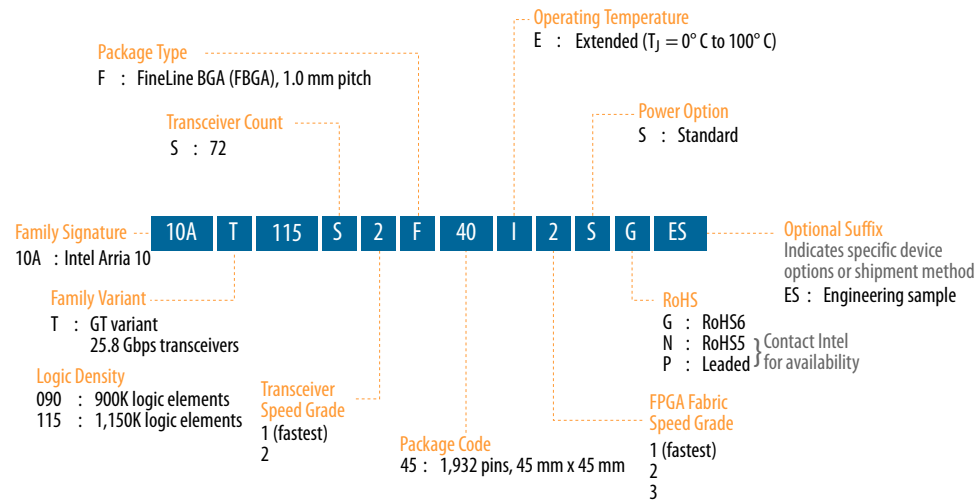
[Intel FPGA Product Selector](#)

Provides the latest information on Intel products.



Available Options

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Resource		Product Line						
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements (LE) (K)		160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multiplier		312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Transceiver		12	12	24	24	36	48	48
GPIO ⁽⁸⁾		288	288	384	384	492	696	696
LVDS Pair ⁽⁹⁾		120	120	168	168	174	324	324
PCIe Hard IP Block		1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-A9 MPCore Processor		Yes	Yes	Yes	Yes	Yes	Yes	Yes

Package Plan

Table 13. Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	—	—	—
SX 220	48	144	6	48	192	12	48	240	12	—	—	—
SX 270	—	—	—	48	192	12	48	312	12	48	336	24
SX 320	—	—	—	48	192	12	48	312	12	48	336	24
continued...												

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software **Pin Migration View**.

Variant	Product Line	Package										
		U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
Intel® Arria® 10 GX	GX 160	↑	↑	↑								
	GX 220	↓	↓	↓								
	GX 270		↓	↓	↑	↑						
	GX 320		↓	↓	↑	↑						
	GX 480			↓	↑	↑						
	GX 570				↑	↑	↑	↑				
	GX 660				↑	↑	↑	↑	↑	↑	↑	↑
	GX 900				↑			↑	↑	↑	↑	↑
	GX 1150				↑			↑	↑	↑	↑	↑
	GT 900										↑	↑
	GT 1150										↓	↓
Intel Arria 10 SX	SX 160	↑	↑	↑								
	SX 220	↓	↓	↓								
	SX 270		↓	↓	↑	↑						
	SX 320		↓	↓	↑	↑						
	SX 480			↓	↑	↑						
	SX 570				↑	↑	↑	↑				
	SX 660				↑	↑	↑	↑				

Note: To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable-precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			18 x 19 Multiplier	27 x 27 Multiplier		
Intel Arria 10 GX	GX 160	156	312	156	156	156
	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 SX	SX 160	156	312	156	156	156
	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830

continued...



Variant	Product Line	Variable-precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			18 x 19 Multiplier	27 x 27 Multiplier		
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable-precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single-Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating-Point Operations per Second (GFLOPs)
Intel Arria 10 GX	GX 160	156	156	156	156	140
	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10 GT	GT 900	1,518	1,518	1,518	1,518	1,366
	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10 SX	SX 160	156	156	156	156	140
	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32-bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened high-performance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

[External Memory Interface Spec Estimator](#)

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.



Related Information

[Intel Arria 10 Device Datasheet](#)

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

[PCS Features](#) on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

[PCS Features](#) on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

[PCS Features](#) on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed

Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



PMA Features

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



Each transceiver channel contains a channel PLL that can be used as the CMU PLL or clock data recovery (CDR) PLL. In CDR mode, the channel PLL recovers the receiver clock and data in the transceiver channel. Up to 80 independent data rates can be configured on a single Intel Arria 10 device.

Table 23. PMA Features of the Transceivers in Intel Arria 10 Devices

Feature	Capability
Chip-to-Chip Data Rates	1 Gbps to 17.4 Gbps (Intel Arria 10 GX devices) 1 Gbps to 25.8 Gbps (Intel Arria 10 GT devices)
Backplane Support	Drive backplanes at data rates up to 12.5 Gbps
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, CFP/CFP2/CFP4
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA
Transmit Pre-Emphasis	4-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss
Decision Feedback Equalizer (DFE)	7-fixed and 4-floating tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments
Variable Gain Amplifier	Optimizes the signal amplitude prior to the CDR sampling and operates in fixed and adaptive modes
Altera Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters—including CTLE, DFE, and variable gain amplifier blocks—that provide optimal link margin without intervention from user logic
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance
Advanced Transmit (ATX) PLL	Low jitter ATX (LC tank based) PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols
Fractional PLLs	On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost
Digitally Assisted Analog CDR	Superior jitter tolerance with fast lock time
Dynamic Partial Reconfiguration	Allows independent control of the Avalon memory-mapped interface of each transceiver channel for the highest transceiver flexibility
Multiple PCS-PMA and PCS-PLD interface widths	8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization width, encoding, and reduced latency

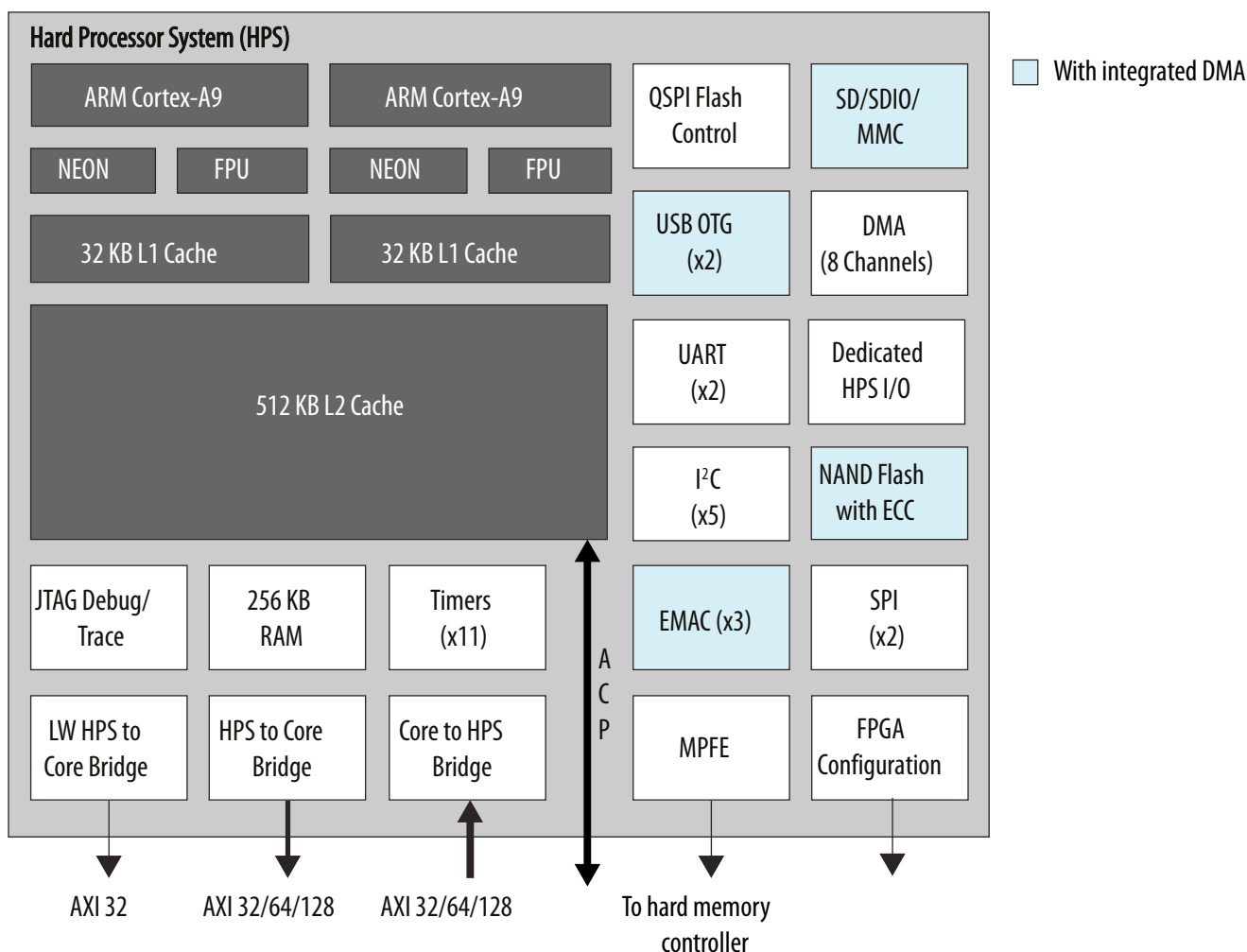
PCS Features

This table summarizes the Intel Arria 10 transceiver PCS features. You can use the transceiver PCS to support a wide range of protocols ranging from 1 Gbps to 25.8 Gbps.



Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



Key Advantages of 20-nm HPS

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
 - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
 - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

Enhanced Configuration and Configuration via Protocol

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) ⁽¹³⁾	Decompression	Design Security ⁽¹⁴⁾	Partial Reconfiguration ⁽¹⁵⁾	Remote System Update
JTAG	1 bit	33	33	—	—	Yes ⁽¹⁶⁾	—
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes ⁽¹⁶⁾	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes ⁽¹⁶⁾	Parallel Flash Loader (PFL) IP core

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⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁶⁾ Partial configuration can be performed only when it is configured as internal host.



The optional power reduction techniques in Intel Arria 10 devices include:

- **SmartVID**—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V_{CC} while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- **Low Static Power Options**—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

Document Revision History for Intel Arria 10 Device Overview

Document Version	Changes
2018.04.09	Updated the lowest V_{CC} from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	<ul style="list-style-type: none">• Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.• Updated maximum frequency supported for half rate QDR II and QDR II + SRAM to 633 MHz in <i>Memory Standards Supported by the Soft Memory Controller</i> table.• Updated transceiver backplane capability to 12.5 Gbps.• Removed transceiver speed grade 5 in <i>Sample Ordering Core and Available Options for Intel Arria 10 GX Devices</i> figure.
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Date	Version	Changes
August 2014	2014.08.18	<ul style="list-style-type: none"> Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620. Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table. Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration. Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller. Added variable precision DSP blocks support for floating-point arithmetic.
June 2014	2014.06.19	Updated number of dedicated I/Os in the HPS block to 17.
February 2014	2014.02.21	Updated transceiver speed grade options for GT devices in Figure 2.
February 2014	2014.02.06	Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps.
December 2013	2013.12.10	<ul style="list-style-type: none"> Updated the HPS memory standards support from LPDDR2 to LPDDR3. Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks .
December 2013	2013.12.02	Initial release.